FAIRCHILD SEMICONDUCTOR™

December 1994
Revised September 2000

74F00
Quad 2-Input NAND Gate

General Description

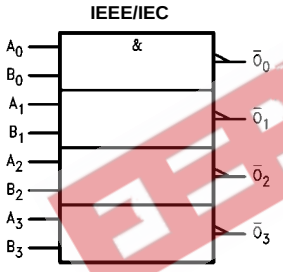
This device contains four independent gates, each of which performs the logic NAND function.

Ordering Code:

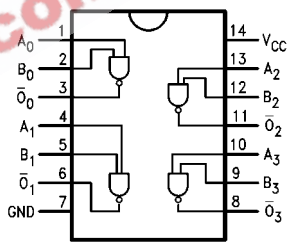
Order Number	Package Number	Package Description
74F00SC	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-120, 0.150 Narrow
74F00SJ	M14D	14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74F00PC	N14A	14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Logic Symbol



Connection Diagram



Unit Loading/Fan Out

Pin Names	Description	U.L. HIGH/LOW	Input I_{IH}/I_{IL} Output I_{OH}/I_{OL}
A_n, B_n	Inputs	1.0/1.0	20 µA/–0.6 mA
$\overline{O}_n$	Outputs	50/33.3	–1 mA/20 mA

Absolute Maximum Ratings(Note 1)

Storage Temperature	−65°C to +150°C
Ambient Temperature under Bias	−55°C to +125°C
Junction Temperature under Bias	−55°C to +150°C
V_{CC} Pin Potential to Ground Pin	−0.5V to +7.0V
Input Voltage (Note 2)	−0.5V to +7.0V
Input Current (Note 2)	−30 mA to +5.0 mA
Voltage Applied to Output	
in HIGH State (with V_{CC} = 0V)	
Standard Output	−0.5V to V_{CC}
3-STATE Output	−0.5V to +5.5V
Current Applied to Output	
in LOW State (Max)	twice the rated I_{OL} (mA)
ESD Last Passing Voltage (Min)	4000V

Recommended Operating Conditions

Free Air Ambient Temperature	0°C to +70°C
Supply Voltage	+4.5V to +5.5V

Note 1: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

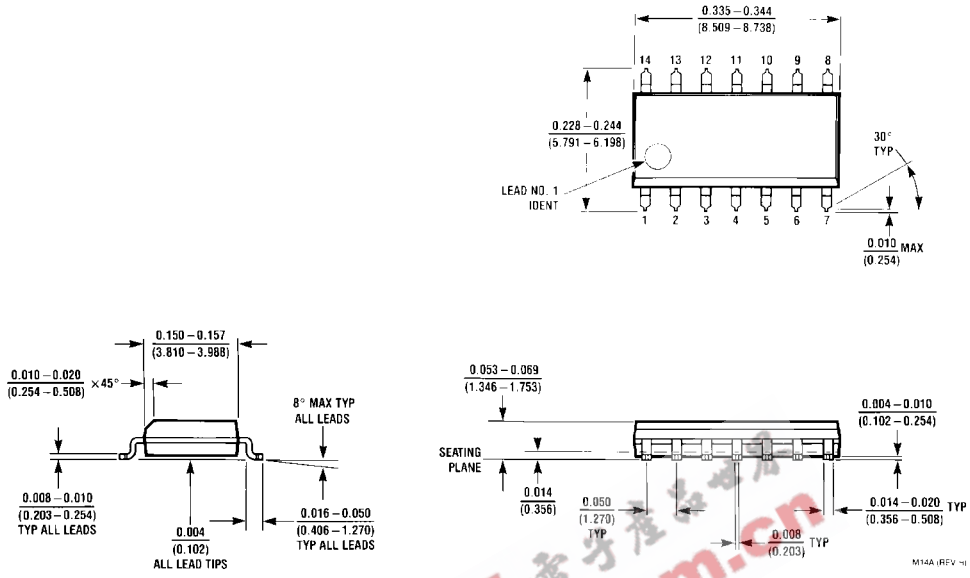
DC Electrical Characteristics

Symbol	Parameter		Min	Typ	Max	Units	V_{CC}	Conditions
V_{IH}	Input HIGH Voltage		2.0			V		Recognized as a HIGH Signal
V_{IL}	Input LOW Voltage				0.8	V		Recognized as a LOW Signal
V_{CD}	Input Clamp Diode Voltage				−1.2	V	Min	I_{IN} = −18 mA
V_{OH}	Output HIGH Voltage	10% V_{CC}	2.5			V	Min	I_{OH} = −1 mA
		5% V_{CC}	2.7					I_{OH} = −1 mA
V_{OL}	Output LOW Voltage	10% V_{CC}			0.5	V	Min	I_{OL} = 20 mA
I_{IH}	Input HIGH Current				5.0	µA	Max	V_{IN} = 2.7V
I_{BVI}	Input HIGH Current Breakdown Test				7.0	µA	Max	V_{IN} = 7.0V
I_{CEX}	Output HIGH Leakage Current				50	µA	Max	V_{OUT} = V_{CC}
V_{ID}	Input Leakage Test		4.75			V	0.0	I_{ID} = 1.9 µA All other pins grounded
I_{OD}	Output Leakage Circuit Current				3.75	µA	0.0	V_{IOD} = 150 mV All other pins grounded
I_{IL}	Input LOW Current				−0.6	mA	Max	V_{IN} = 0.5V
I_{OS}	Output Short-Circuit Current		−60		−150	mA	Max	V_{OUT} = 0V
I_{CCH}	Power Supply Current			1.9	2.8	mA	Max	V_O = HIGH
I_{CCL}	Power Supply Current			6.8	10.2	mA	Max	V_O = LOW

AC Electrical Characteristics

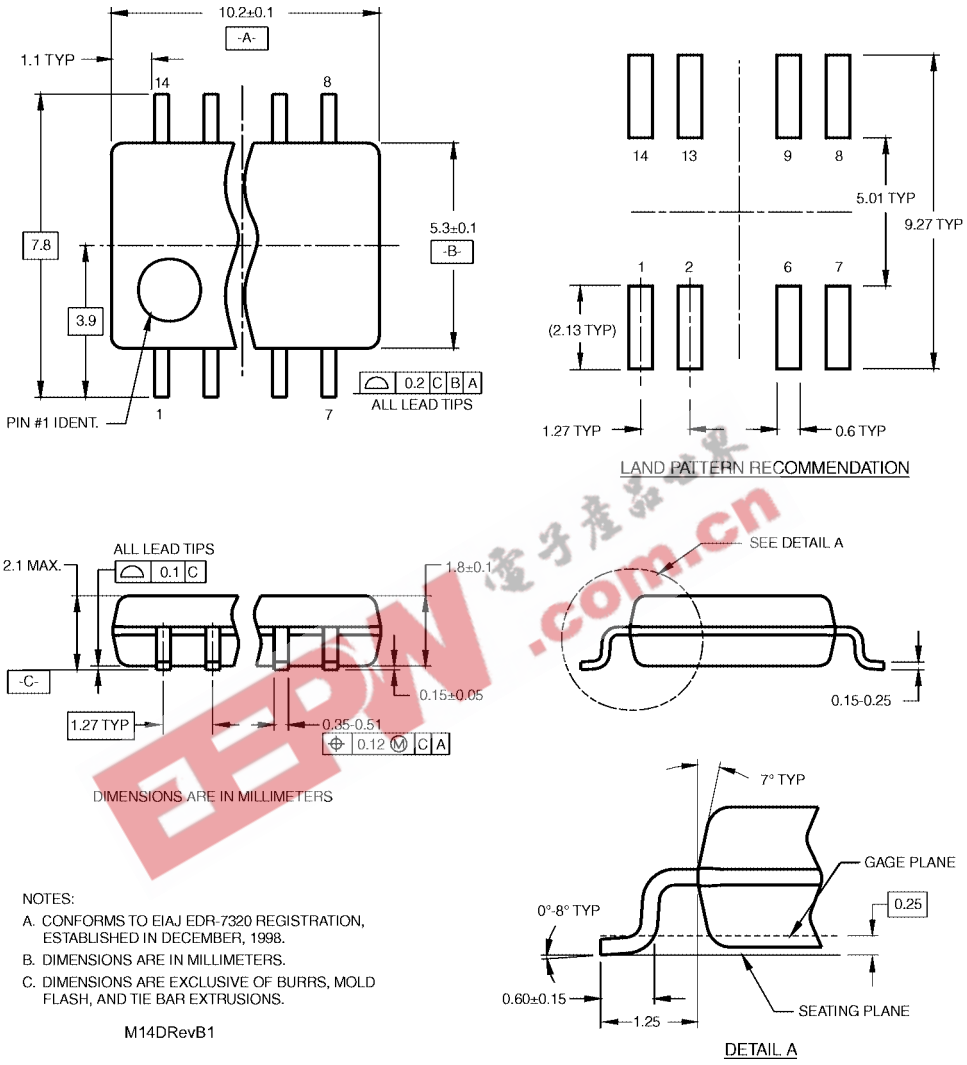
Symbol	Parameter	T_A = +25°C, V_{CC} = +5.0V, C_L = 50 pF			T_A = −55°C to +125°C, V_{CC} = +5.0V, C_L = 50 pF		T_A = 0°C to +70°C, V_{CC} = +5.0V, C_L = 50 pF		Units
		Min	Typ	Max	Min	Max	Min	Max	
t_{PLH}	Propagation Delay	2.4	3.7	5.0	2.0	7.0	2.4	6.0	ns
t_{PHL}	A_n, B_n to $\overline{O}_n$	1.5	3.2	4.3	1.5	6.5	1.5	5.3	

Physical Dimensions inches (millimeters) unless otherwise noted



14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-120, 0.150 Narrow
Package Number M14A

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



NOTES:

A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.

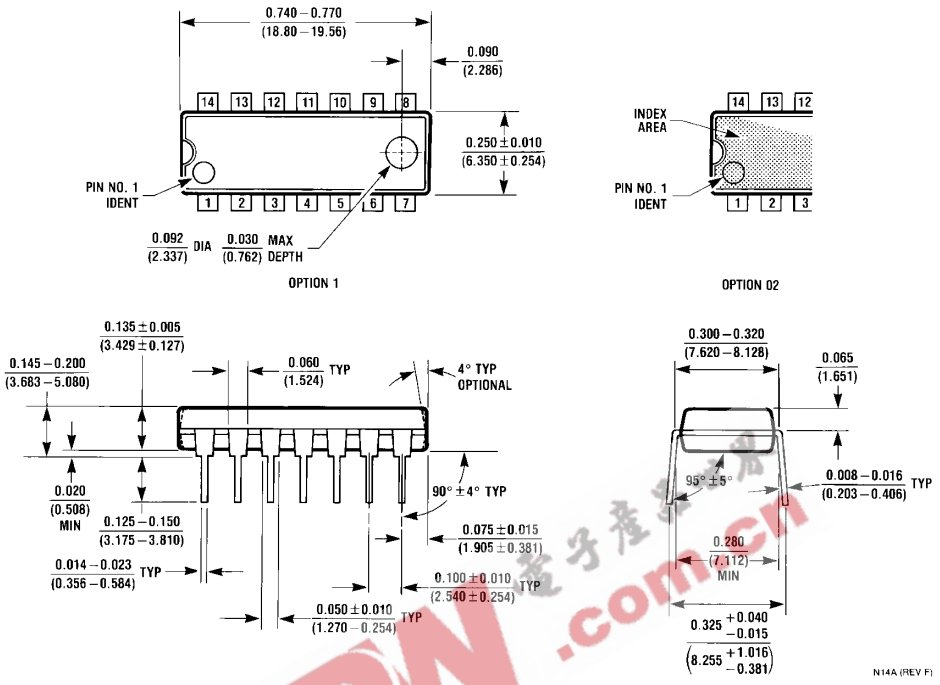
B. DIMENSIONS ARE IN MILLIMETERS.

C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M14DRevB1

14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M14D

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide
Package Number N14A

LIFE SUPPORT POLICY

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1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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